

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT																
NATURE OF CONVEYANCE:	ASSIGNMENT																
CONVEYING PARTY DATA																	
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr><td>Hyung Soo Kim</td><td>12/17/2007</td></tr> <tr><td>Kun Woo Park</td><td>12/17/2007</td></tr> <tr><td>Yong Ju Kim</td><td>12/17/2007</td></tr> <tr><td>Jong Woon Kim</td><td>12/17/2007</td></tr> <tr><td>Hee Woong Song</td><td>12/17/2007</td></tr> <tr><td>Ic Su Oh</td><td>12/17/2007</td></tr> <tr><td>Tae Jin Hwang</td><td>12/17/2007</td></tr> </tbody> </table>		Name	Execution Date	Hyung Soo Kim	12/17/2007	Kun Woo Park	12/17/2007	Yong Ju Kim	12/17/2007	Jong Woon Kim	12/17/2007	Hee Woong Song	12/17/2007	Ic Su Oh	12/17/2007	Tae Jin Hwang	12/17/2007
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RECEIVING PARTY DATA																	
Name:	HYNIX SEMICONDUCTOR INC.																
Street Address:	San 136-1, Ami-ri, Bubal-eub																
Internal Address:	Gyeonggi-do																
City:	Ichon																
State/Country:	REPUBLIC OF KOREA																
Postal Code:	467-860																
PROPERTY NUMBERS Total: 1																	
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11966250</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11966250												
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CORRESPONDENCE DATA																	
Fax Number:	(214)978-3099																
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>																	
Email:	scarlett.k.pereida@bakernet.com																
Correspondent Name:	Noel C. Gillespie																
Address Line 1:	2001 Ross Avenue, Suite 2300																
Address Line 2:	Baker & McKenzie																
Address Line 4:	Dallas, TEXAS 75201																
ATTORNEY DOCKET NUMBER:	95210324.200149																

CH \$40.00 11966250

NAME OF SUBMITTER:

Noel C. Gillespie

Total Attachments: 4

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ASSIGNMENT

WHEREAS, I the undersigned inventor of residence as listed, have invented certain new and useful improvements as below entitled, for which an application for United States Letters Patent is made, said application having been designated as set forth below and filed on or about the date set forth below; and

WHEREAS, Hynix Semiconductor Inc. (hereinafter referred to as "Assignee"),

with an address of: San 136-1, Ami-ri, Bubal-eub, Ichon-si,
Gyeonggi-do 467-860, Republic of Korea

desires to acquire the entire right, title and interest in and to the invention, and in and to the said application and any Letters Patent(s) that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I assign to Assignee, all right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all divisions, reissues, continuations, continuations-in-part and extensions thereof; and I authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patents resulting therefrom, insofar as my interest is concerned, to Assignee.

I also assign to Assignee, all right, title and interest in and to the invention disclosed in said application throughout the world, including the right to file applications and obtain patents, utility models, industrial models and designs for said invention in its own name throughout the world, including all rights to publish cautionary notices reserving ownership of said invention and all rights to register said invention in appropriate registries; and I further agree to execute any and all powers of attorney, applications, assignments, declarations, affidavits, and any other papers in connection therewith necessary to perfect such right, title and interest in Assignee.

I will communicate to Assignee any facts known to us respecting any improvements; and, at the expense of Assignee, I will testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, continuation-in-part, reissue and substitute applications, make lawful oaths and declarations, and generally do everything possible to vest title in Assignee and to aid Assignee to obtain and enforce proper protection for said invention in all countries.

This Assignment shall be binding on the parties' successors, assigns and legal representatives.

Invention Name: **APPARATUS FOR TRANSMITTING SIGNAL IN
SEMICONDUCTOR INTEGRATED CIRCUIT**

Serial No.: _____

Date Filed: _____

I hereby grant JOHN G. FLAIM, Registration No. 37,323, BRIAN C. McCORMACK, Registration No. 36,601, WILLIAM D. McSPADDEN, Registration No. 44,234, JAMES H. ORTEGA, Registration No. 50,554, RICHARD V. WELLS, Registration No. 53,757, HOWARD WISNIA, Registration No. 37,502, NOEL C. GILLESPIE, Registration No. 47,596, ROGER C. KUAN, Registration No. 56,558, KEVIN O'BRIEN, Registration No. 30,578, JAMES P. CONLEY, Registration No. 52,459, and all practitioners with the firm of Baker & McKenzie LLP (Customer Number 23562) with an office at 2001 Ross Avenue, Suite 2300, Dallas, TX 75201, the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

The undersigned further declares that all statements made herein of his/her own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful and false statements may jeopardize the validity of the application or any patent issued thereon.

Signature of Inventor: _____ *Hyungsoo Kim* _____

Inventor(s) Name: _____ **Hyung Soo, KIM** _____

Residence: San 136-1, Ami-ri, Bubal-eub, Ichon-si,
 Gyeonggi-do 467-860, Republic of Korea

Citizenship: _____ **Korean** _____

Date: _____ *07.12.17* _____

Signature of Inventor: Kunwoo park
Inventor(s) Name: Kun Woo, PARK
Residence: San 136-1, Ami-ri, Bubal-eub, Ichon-si,
Gyeonggi-do 467-860, Republic of Korea
Citizenship: Korean
Date: 07.12.17

Signature of Inventor: Yongju Kim
Inventor(s) Name: Yong Ju, KIM
Residence: San 136-1, Ami-ri, Bubal-eub, Ichon-si,
Gyeonggi-do 467-860, Republic of Korea
Citizenship: Korean
Date: 07.12.17

Signature of Inventor: Jong won Kim
Inventor(s) Name: Jong Woon, KIM
Residence: San 136-1, Ami-ri, Bubal-eub, Ichon-si,
Gyeonggi-do 467-860, Republic of Korea
Citizenship: Korean
Date: 07.12.17

Signature of Inventor: Hee woong, Song
Inventor(s) Name: Hee Woong, SONG
Residence: San 136-1, Ami-ri, Bubal-eub, Ichon-si,
Gyeonggi-do 467-860, Republic of Korea
Citizenship: Korean
Date: 07.12.17

Signature of Inventor: IcSu OH
Inventor(s) Name: Ic Su, OH
Residence: San 136-1, Ami-ri, Bubal-eub, Ichon-si,
Gyeonggi-do 467-860, Republic of Korea
Citizenship: Korean
Date: 07.12.17

Signature of Inventor: TaeJin HWANG
Inventor(s) Name: Tae Jin, HWANG
Residence: San 136-1, Ami-ri, Bubal-eub, Ichon-si,
Gyeonggi-do 467-860, Republic of Korea
Citizenship: Korean
Date: 07.12.17

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